DATA SHEET

74ABT377A
Octal D-type flip-flop with enable

Product specification
Replaces data sheet 74ABT377 of 1995 Sep 06
IC23 Data Handbook

1997 Feb 26

Philips
Semiconductors

PHILIPS

Octal D-type flip-flop with enable 74ABT377A

FEATURES

- Ideal for addressable register applications
- 8-bit positive edge-triggered register
- Enable for address and data synchronization applications
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per Jedec JC40.2 Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model
- Power-up reset

DESCRIPTION

The 74ABT377A high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT377A has 8 edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered clock (CP) input loads all flip-flops simultaneously when the Enable ($\overline{E}$) input is Low.

The register is fully edge triggered. The state of each D input, one set-up time before the Low-to-High clock transition, is transferred to the corresponding flip-flop's Q output.

The $\overline{E}$ input must be stable one setup time prior to the Low-to-High clock transition for predictable operation.

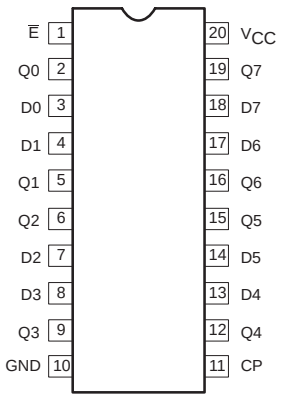
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T_{amb} = 25°C; GND = 0V	TYPICAL	UNIT
t_{PLH} t_{PHL}	Propagation delay CP to Qn	C_L = 50pF; V_{CC} = 5V	3.1 3.6	ns
C_{IN}	Input capacitance	V_I = 0V or V_{CC}	4	pF
I_{CCH}	Total current supply	Outputs High; V_{CC} = 5.5V	500	nA

ORDERING INFORMATION

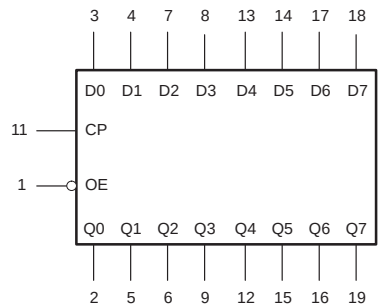
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic DIP	–40°C to +85°C	74ABT377A N	74ABT377A N	SOT146-1
20-Pin plastic SO	–40°C to +85°C	74ABT377A D	74ABT377A D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +85°C	74ABT377A DB	74ABT377A DB	SOT339-1
20-Pin Plastic TSSOP Type I	–40°C to +85°C	74ABT377A PW	74ABT377PWA DH	SOT360-1

PIN CONFIGURATION



SA00155

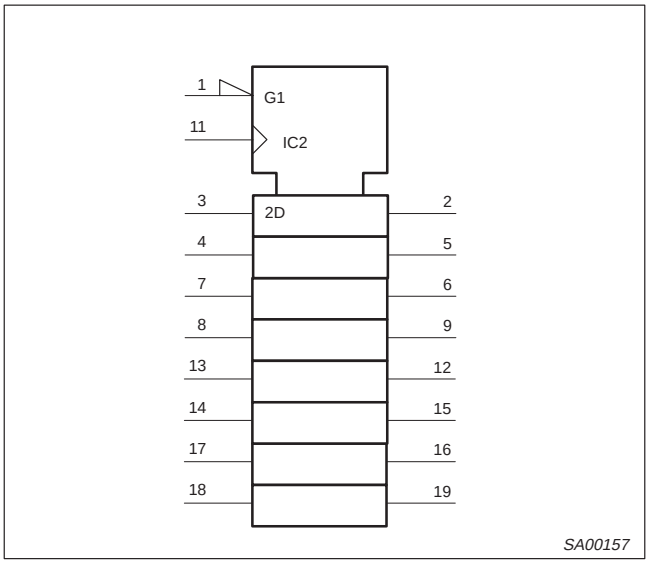
LOGIC SYMBOL



SA00152

Octal D-type flip-flop with enable 74ABT377A

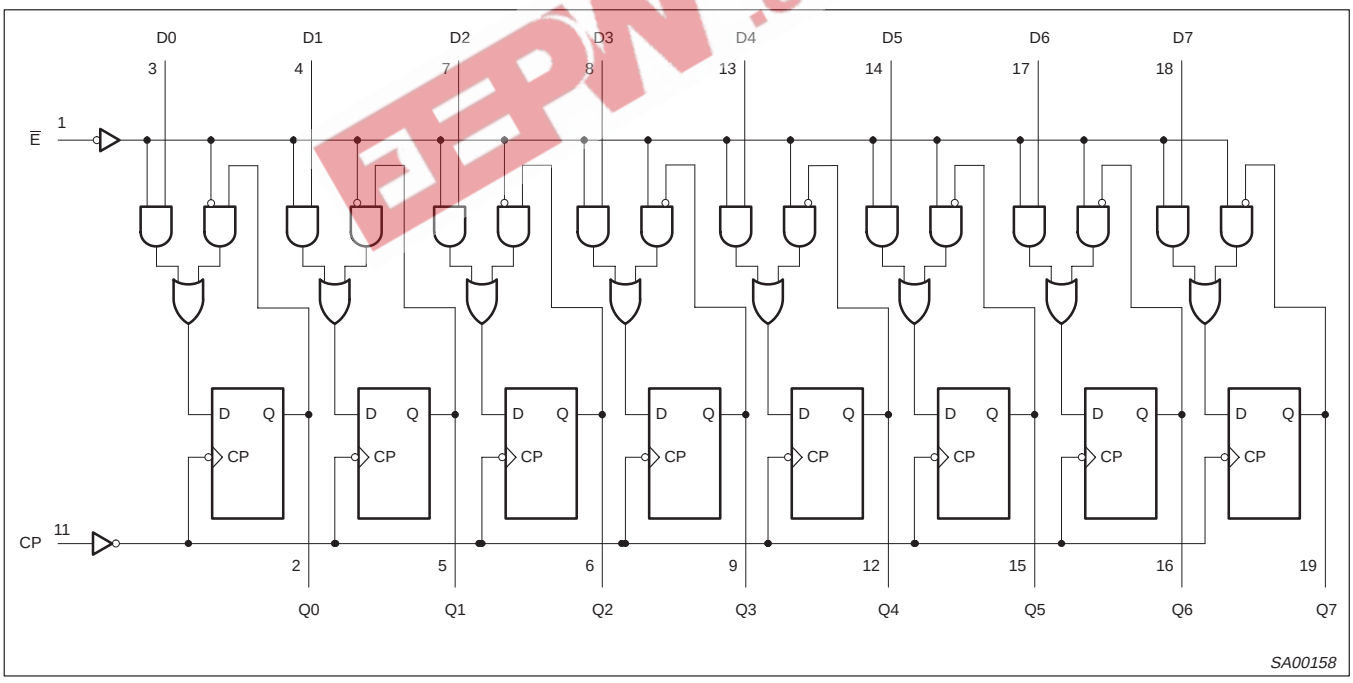
LOGIC SYMBOL (IEEE/IEC)



PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1	$\overline{E}$	Enable input (active–Low)
3, 4, 7, 8, 13, 14, 17, 18	D0-D7	Data inputs
2, 5, 6, 9, 12, 15, 16, 19	Q0-Q7	Data outputs
11	CP	Clock Pulse input (active rising edge)
10	GND	Ground (0V)
20	V_{CC}	Positive supply voltage

LOGIC DIAGRAM



FUNCTION TABLE

INPUTS			OUTPUTS	OPERATING MODE
$\overline{E}$	CP	Dn	Qn	
l	↑	h	H	Load “1”
l	↑	l	L	Load “0”
h H	↑ X	X X	no change no change	Hold (do nothing)

H = High voltage level
h = High voltage level one set-up time prior to the Low-to-High clock transition
L = Low voltage level
l = Low voltage level one set-up time prior to the Low-to-High clock transition
X = Don’t care
↑ = Low-to-High clock transition

ABSOLUTE MAXIMUM RATINGS[1, 2]

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +7.0	V
I_{IK}	DC input diode current	$V_I < 0$	–18	mA
V_I	DC input voltage[3]		–1.2 to +7.0	V
I_{OK}	DC output diode current	$V_O < 0$	–50	mA
V_{OUT}	DC output voltage[3]	output in Off or High state	–0.5 to +5.5	V
I_{OUT}	DC output current	output in Low state	128	mA
T_{stg}	Storage temperature range		–65 to 150	°C

NOTES:
1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.
3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
		MIN	MAX	
V_{CC}	DC supply voltage	4.5	5.5	V
V_I	Input voltage	0	V_{CC}	V
V_{IH}	High-level input voltage	2.0		V
V_{IL}	Low-level input voltage		0.8	V
I_{OH}	High-level output current		–32	mA
I_{OL}	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	5	ns/V
T_{amb}	Operating free-air temperature range	–40	+85	°C

DC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T_{amb} = +25°C			T_{amb} = –40°C to +85°C		
			MIN	TYP	MAX	MIN	MAX	
V_{IK}	Input clamp voltage	V_{CC} = 4.5V; I_{IK} = –18mA		–0.9	–1.2		–1.2	V
V_{OH}	High–level output voltage	V_{CC} = 4.5V; I_{OH} = –3mA; V_I = V_{IL} or V_{IH}	2.5	2.9		2.5		V
		V_{CC} = 5.0V; I_{OH} = –3mA; V_I = V_{IL} or V_{IH}	3.0	3.4		3.0		V
		V_{CC} = 4.5V; I_{OH} = –32mA; V_I = V_{IL} or V_{IH}	2.0	2.4		2.0		V
V_{OL}	Low-level output voltage	V_{CC} = 4.5V; I_{OL} = 64mA; V_I = V_{IL} or V_{IH}		0.42	0.55		0.55	V
V_{RST}	Power-up output low voltage[3]	V_{CC} = 5.5V; I_O = 1mA; V_I = GND or V_{CC}		0.13	0.55		0.55	V
I_I	Input leakage current	V_{CC} = 5.5V; V_I = GND or 5.5V		±0.01	±1.0		±1.0	µA
I_{OFF}	Power-off leakage current	V_{CC} = 0.0V; V_O or $V_I \leq$ 4.5V		±5.0	±100		±100	µA
I_{CEX}	Output High leakage current	V_{CC} = 5.5V; V_O = 5.5V; V_I = GND or V_{CC}		5.0	50		50	µA
I_O	Output current[1]	V_{CC} = 5.5V; V_O = 2.5V	–50	–100	–180	–50	–180	mA
I_{CCH}	Quiescent supply current	V_{CC} = 5.5V; Outputs High, V_I = GND or V_{CC}		0.5	250		250	µA
I_{CCL}		V_{CC} = 5.5V; Outputs Low, V_I = GND or V_{CC}		24	30		30	mA
ΔI_{CC}	Additional supply current per input pin[2]	V_{CC} = 5.5V; one input at 3.4V, other inputs at V_{CC} or GND		0.5	1.5		1.5	mA

NOTES:
1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
2. This is the increase in supply current for each input at 3.4V.
3. For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.

AC CHARACTERISTICS

GND = 0V, $t_R = t_F$ = 2.5ns, C_L = 50pF, R_L = 500Ω

SYMBOL	PARAMETER	WAVEFORM	LIMITS[1]					UNIT
			T_{amb} = +25°C V_{CC} = +5.0V			T_{amb} = -40 to +85°C V_{CC} = +5.0V ±0.5V		
			MIN	TYP	MAX	MIN	MAX	
f_{MAX}	Maximum clock frequency	1	150	250		150		MHz
t_{PLH} t_{PHL}	Propagation delay CP to Qn	1	1.8 2.2	3.1 3.6	4.0 4.7	1.8 2.2	4.8 4.9	ns

NOTE:
1. Limits may vary among suppliers.

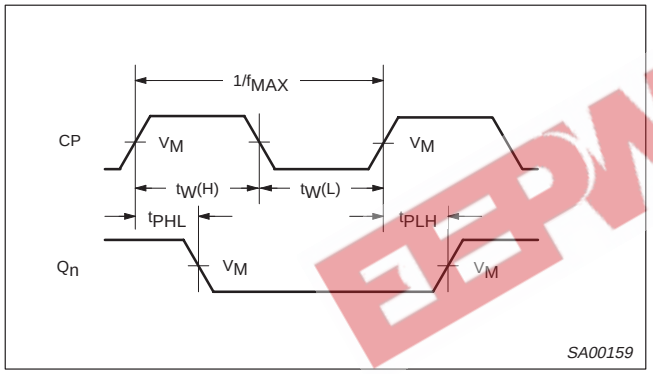
AC SETUP REQUIREMENTS

GND = 0V, $t_R = t_F$ = 2.5ns, C_L = 50pF, R_L = 500Ω

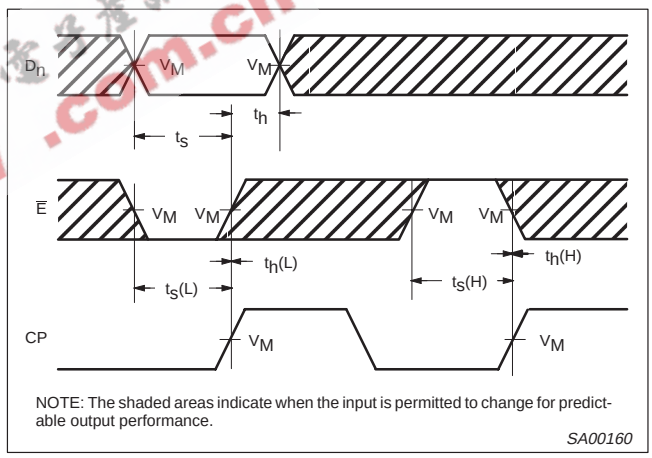
SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			T_{amb} = +25°C, V_{CC} = +5.0V		T_{amb} = -40 to +85°C, V_{CC} = +5.0V ±0.5V	
			MIN	TYP	MIN	
$t_s(H)$ $t_s(L)$	Setup time, High or Low Dn to CP	2	1.5 1.5	0.7 0.5	1.5 1.5	ns
$t_h(H)$ $t_h(L)$	Hold time, High or Low Dn to CP	2	1.0 1.0	–0.4 –0.6	1.0 1.0	ns
$t_s(H)$ $t_s(L)$	Setup time, High or Low $\overline{E}$ to CP	2	2.0 2.0	1.1 1.0	2.0 2.0	ns
$t_h(H)$ $t_h(L)$	Hold time, High or Low $\overline{E}$ to CP	2	1.0 1.0	–0.9 –0.1	1.0 1.0	ns
$t_w(H)$ $t_w(L)$	Clock Pulse width High or Low	1	1.5 2.0	0.7 1.0	1.5 2.0	ns

AC WAVEFORMS

V_M = 1.5V, V_{IN} = GND to 3.0V

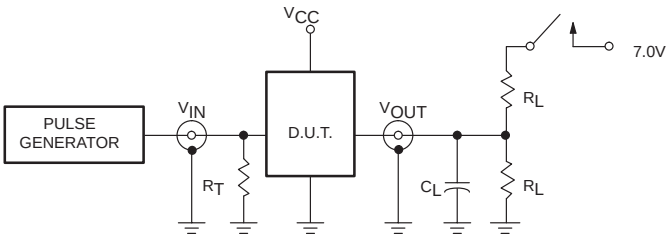


Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width and Maximum Clock Frequency

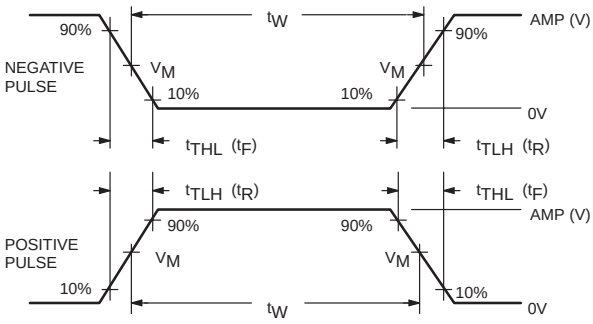


Waveform 2. Data and Enable Setup and Hold Times

TEST CIRCUIT AND WAVEFORM



Test Circuit for 3-State Outputs



V_M = 1.5V

Input Pulse Definition

SWITCH POSITION

TEST	SWITCH
All	open

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.

C_L = Load capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

FAMILY	INPUT PULSE REQUIREMENTS				
	Amplitude	Rep. Rate	t_W	t_R	t_F
74ABT	3.0V	1MHz	500ns	2.5ns	2.5ns

SA00057

Octal D-type flip-flop with enable 74ABT377A

DEFINITIONS

Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

Philips Semiconductors
811 East Arques Avenue
P.O. Box 3409
Sunnyvale, California 94088–3409
Telephone 800-234-7381

Let's make things better.

Philips Semiconductors

PHILIPS

DIP20: plastic dual in-line package; 20 leads (300 mil) SOT146-1

SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm **SOT339-1**

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm SOT360-1